	Subclass	ISSUE CLASSIFICATION
09/3	Class	ISSUE CLAS

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PATENT NUMBER

U.S. UTILITY Patent Application

O.I.P.E. PATENT DATE SCANNED SP3

X APPLICATION NO. CONT/PRIOR CLASS SUBCLASS ART UNIT **EXAMINER** 09/992387 257 2811,

Anthony Coyle Milton Buschbom

Flip-chip on film assembly for ball grid array packages

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CLASS	SUBCLASS	CLASS	CROSS REFERENCE(S) CLASS SUBCLASS (ONE SUBCLASS PER BLOCK)					
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TERMINAL DISCLAIMER	DRAWINGS		CLAIMS ALLOWED		
	Sheets Drwg.	Figs. Drwg.	Print Fig.	Total Claims	Print Claim for O.G.
The term of this patent subsequent to(date)				NOTICE OF ALL	OWANCE MAILED
has been disclaimed. The term of this patent shall not extend beyond the expiration date of U.S Patent. No.	. (Assistant	Examiner)	(Date)	-	
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